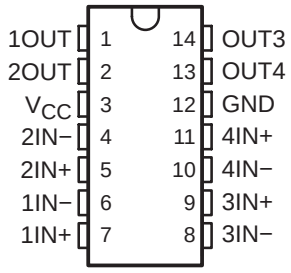
- **Qualification in Accordance With AEC-Q100†**
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **Single Supply or Dual Supplies**
- **Low Supply-Current Drain Independent of Supply Voltage . . . 0.8 mA Typ**
- **Low Input Bias Current . . . 25 nA Typ**
- **Low Input Offset Current . . . 2 nA Typ**
- **Low Input Offset Voltage . . . 2 mV Typ**
- **Common-Mode Input Voltage Range Includes Ground**
- **Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . . ±36 V**
- **Low Output Saturation Voltage**
- **Output Compatible With TTL, MOS, and CMOS**
- **For Single Version in SOT23-5, See TL331**

† Contact factory for details. Q100 qualification data available on request.

D OR PW PACKAGE
(TOP VIEW)



description/ordering information

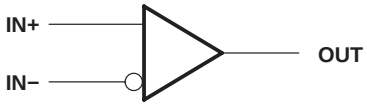
This device consists of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies is possible, as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

ORDERING INFORMATION

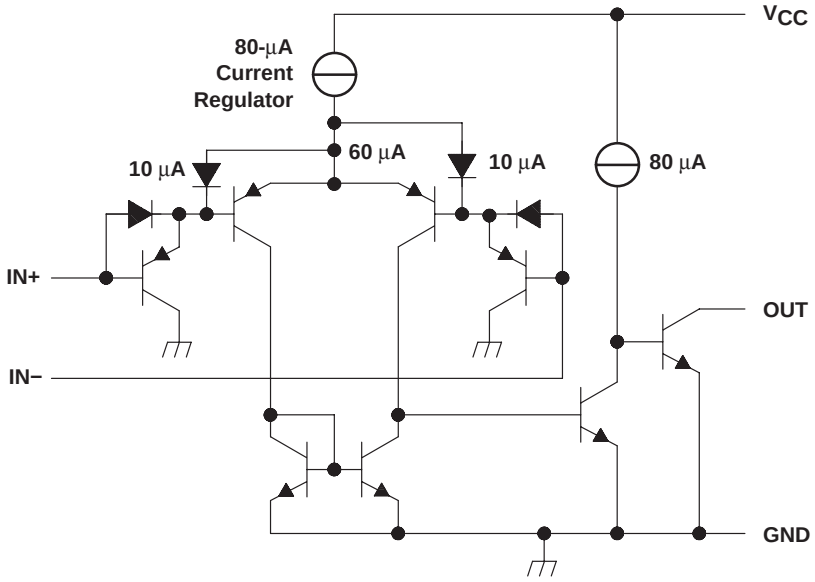
T_A	V_{IO}max AT 25°C	MAX V_{CC}	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 125°C	7 mV	30 V	SOIC (D)	Reel of 2500	LM2901QDRQ1	2901Q1
			TSSOP (PW)	Reel of 2000	LM2901QPWRQ1	2901Q1
−40°C to 125°C	7 mV	32 V	SOIC (D)	Reel of 2500	LM2901VQDRQ1	2901VQ1
			TSSOP (PW)	Reel of 2000	LM2901VQPWRQ1	2901VQ1
−40°C to 125°C	2 mV	32 V	SOIC (D)	Reel of 2500	LM2901AVQDRQ1	2901AVQ
			TSSOP (PW)	Reel of 2000	LM2901AVQPWRQ1	2901AVQ

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol (each comparator)



schematic (each comparator)



All current values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	36 V
Differential input voltage, V_{ID} (see Note 2)	±36 V
Input voltage range, V_I (either input)	−0.3 V to 36 V
Output voltage, V_O	36 V
Output current, I_O	20 mA
Duration of output short circuit to ground (see Note 3)	Unlimited
Package thermal impedance, θ_{JA} (see Notes 4 and 5): D package	86°C/W
PW package	113°C/W
Operating virtual junction temperature, T_J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.
2. Differential voltages are at IN+ with respect to IN−.
3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
5. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		T_A‡	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	$V_{IC} = V_{ICR}$(min), V_O = 1.4 V, V_{CC} = 5 V to MAX§	Non-A devices	25°C		2	7	mV
				Full range			15	
			A-suffix devices	25°C		1	2	
				Full range			4	
I_{IO}	Input offset current	V_O = 1.4 V		25°C		5	50	nA
				Full range			200	
I_{IB}	Input bias current	V_O = 1.4 V		25°C		−25	−250	nA
				Full range			−500	
V_{ICR}	Common-mode input-voltage range			25°C	0 to V_{CC}−1.5			V
				Full range	0 to V_{CC}−2			
A_{VD}	Large-signal differential-voltage amplification	V_{CC} = 15 V, V_O = 1.4 V to 11.4 V, $R_L \geq 15\ k\Omega$ to V_{CC}		25°C	25	100		V/mV
I_{OH}	High-level output current	V_{ID} = 1 V	V_{OH} = 5 V	25°C		0.1	50	nA
			$V_{OH} = V_{CC}$ MAX§	Full range			1	µA
V_{OL}	Low-level output voltage	V_{ID} = −1 V,	I_{OL} = 4 mA	25°C		150	400	mV
				Full range			700	
I_{OL}	Low-level output current	V_{ID} = −1 V,	V_{OL} = 1.5 V	25°C	6	16		mA
I_{CC}	Supply current (four comparators)	V_O = 2.5 V, No load	V_{CC} = 5 V	25°C		0.8	2	mA
			V_{CC} = MAX§			1	2.5	

† All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
‡ Full range (MIN to MAX) for LM2901 is −40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
§ V_{CC} MAX = 30 V for non-V devices and 32 V for V-suffix devices.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
Response time	R_L connected to 5 V through 5.1 kΩ, C_L = 15 pF¶, See Note 6	100-mV input step with 5-mV overdrive		1.3		µs
		TTL-level input step		0.3		

¶ C_L includes probe and jig capacitance.
NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

PACKAGING INFORMATION

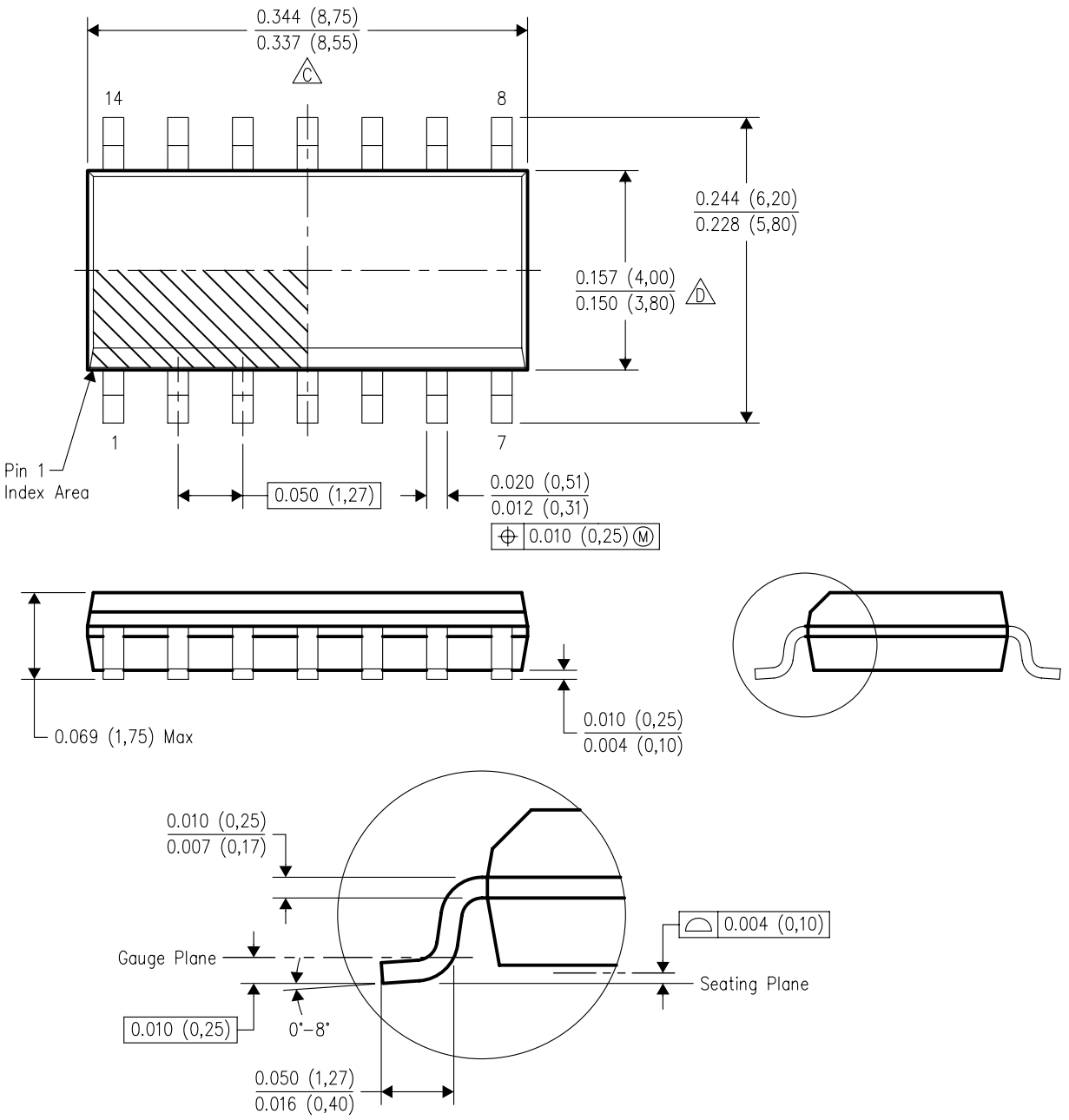
Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
LM2901AVQDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM2901AVQPWRQ1	ACTIVE	TSSOP	PW	14	2000	TBD	CU NIPDAU	Level-1-250C-UNLIM
LM2901QDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM2901QPWRQ1	ACTIVE	TSSOP	PW	14	2000	TBD	CU NIPDAU	Level-1-250C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

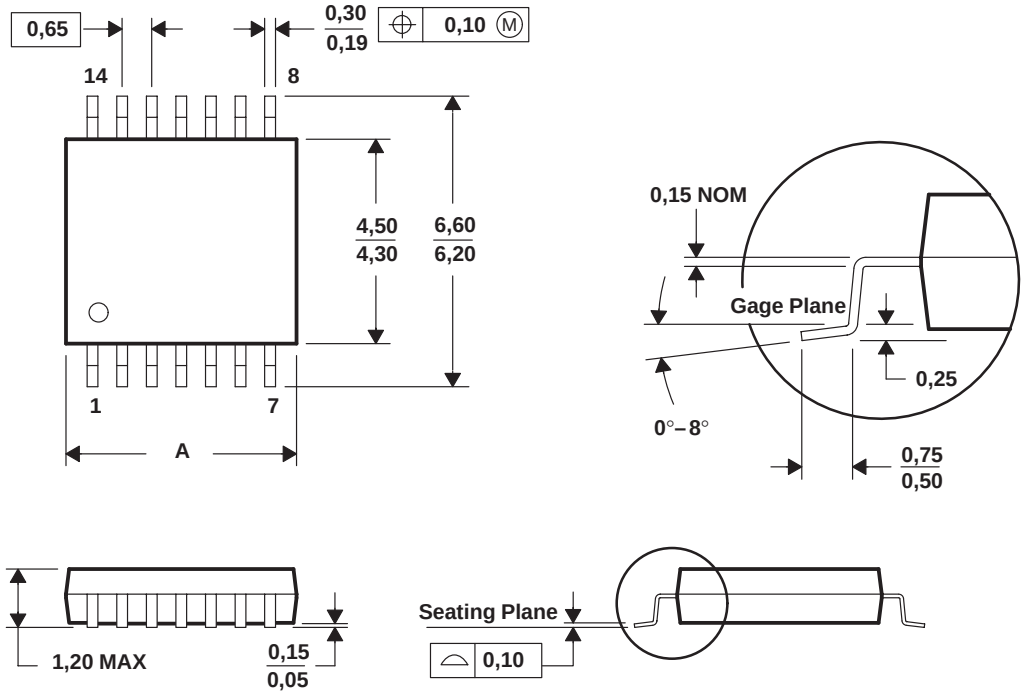
D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AB.

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265